



Seiko Seiki STP-301, STP-451

Technical Specifications

Item		STP-301 series		STP-451 series			
Flange size ^{*1}	Inlet port flange	ICF152/VG100/ISO10 0		ICF203/VG150/ISO16 0			
	Outlet port flange	KF25					
Pumping speed ^{*2}	N ₂	L/s	300	480			
	He	L/s	280	460			
	H ₂	L/s	300	460			
Compression ratio	N ₂		>10 ⁸				
	He		5 x 10 ⁵				
	H ₂		2 x 10 ⁴				
Ultimate pressure Pa (Torr)	Without anti-corrosion treatment		10 ⁻⁸ (10 ⁻¹⁰)	: ICF flange			
	Chemical specific type		6.5 x 10 ⁻⁶ (5 x 10 ⁻⁸)	: VG/ISO flange			
Maximum working pressure	Pa (Torr)	6.7 x 10 ⁻² (5 x 10 ⁻⁴)		: Natural air cooling			
Allowable backing pressure	Pa (Torr)	13 (0.1)		: Natural air cooling			
Rated speed	rpm	25,000 to 48,000					
Starting time	min	3					
Stopping time	min	3					
Vibration	μ m O·P	<0.01 (at 48,000 rpm)					
Noise	dB	<50 (at 48,000 rpm)					
Baking temperature	°C	<120					
Lubricating oil		Not necessary					
Installation position		Free					
Cooling method		Natural air cooling (Water/air cooling: for baking/gas suction)					
Standard backing pump	L/min	240					
Mass	kg	11		12			
Dimensions	mm	φ 180x230		φ 180x200			
Ambient temperature range	°C	0 to 40					
Storage temperature range	°C	- 25 to + 55					

The values shown in the table are typical; they are not guaranteed.

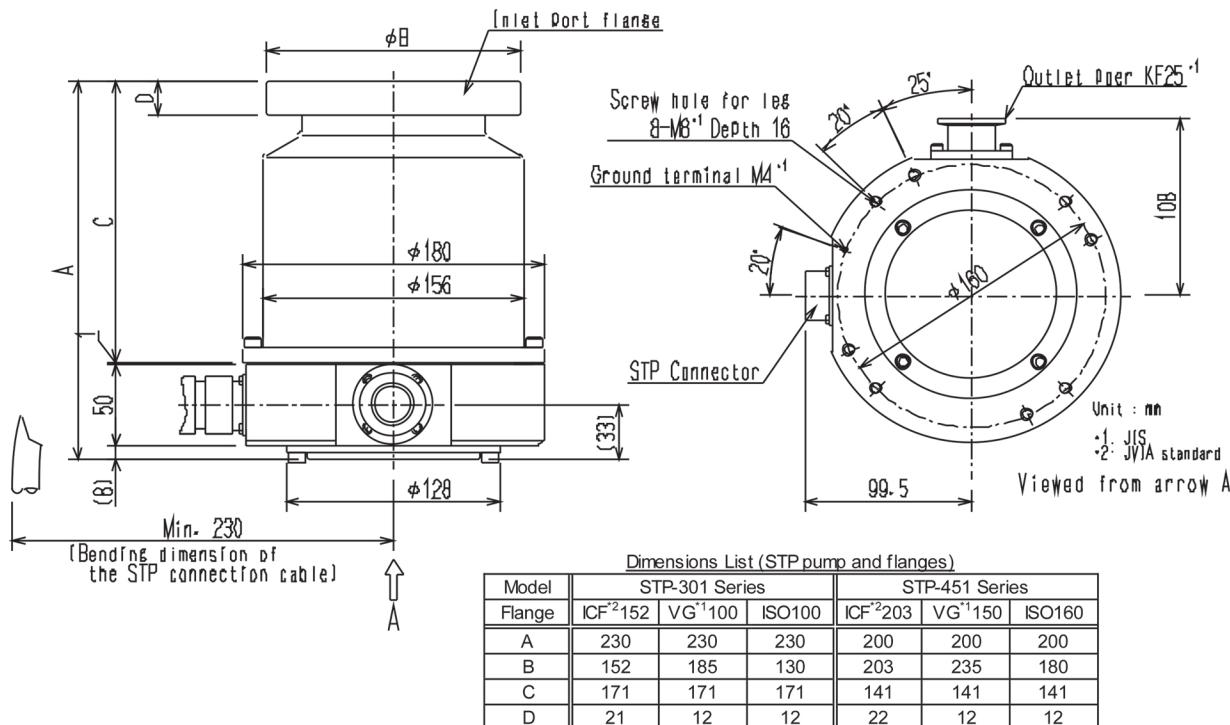
^{*1} :ICF (JVIA standard), VG, KF (JIS)

^{*2}: At 48,000 rpm. The performance varies with the rated speed



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Dimensions



External Appearance of the STP Pump [without Anti-Corrosion Treatment] (Example: STP-301)

Features & Benefits

- oil free
- low vibration
- high reliability
- maintenance free
- increased life
- advanced controller design
- compact design
- small footprint
- advanced rotor technology
- installation in any orientation

Applications

- plasma etch • electron cyclotron resonance • film deposition • ion implantation • sputtering • MBE • diffusion • photo resist stripping
- crystal growth • water inspection • load-lock chambers.